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10/065568



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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10065568	FILING DATE 10/31/2002	CLASS 438	SUBCLASS 684	GAU 2842	282A	EXAMINER LUHRS
**APPLICANTS: Chen Kuo-Ming; Liu Hung-Min;						
**CONTINUING DATA VERIFIED:						
** FOREIGN APPLICATIONS VERIFIED:						
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO NAUP0482USA		
TITLE : Solder bump structure and laser repair process for memory device <small>U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)</small>						

NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
				Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner		DRAWING	
Amount Due	Date Paid			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
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